



**NVIDIA®**

**SC10:**

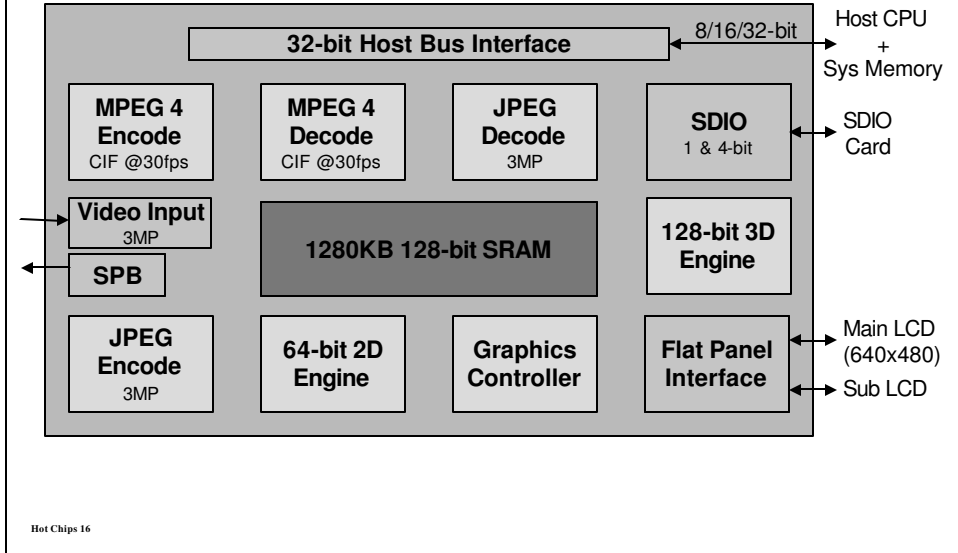
**A Video Processor And Pixel-Shading GPU for Handheld Devices**

***Edward Hutchins***

## What is SC10?

- **Companion chip for handheld devices**  
(Cell-phones, PDAs, dedicated game devices)
- **Assumes external host processor + memory**
- **Accelerates image, video, 2D and 3D processing**
- **Designed for battery-powered applications**
- **Small package**
- **Host interface scales from 8-bit to full 32-bit I/O**

# SC10 Block Diagram



## Multimedia Features

- Full-duplex hardware MPEG4 codec
- CIF MPEG4 encode @ 30fps
- CIF MPEG4 decode @ 30fps
- MPEG4 simple profile level 0, 1, 2, 3
- 3MP camera support
- 1.3MP preview @ 24fps
- 640x480 display support
- 72MHz camera clock
- Serial Peripheral Bus for camera control

## 3D Design Goals

- **Efficient use of power**
- **Efficient use of area**
- **Broad API support**
  - **OpenGL-ES**
  - **D3D Mobile**
  - **non-3D uses (signal/image processing)**
- **Modular, expandable architecture**
  - **quick response as the market grows**
  - **simple, consistent interfaces and data-types**
  - **fully programmable to support evolving APIs**

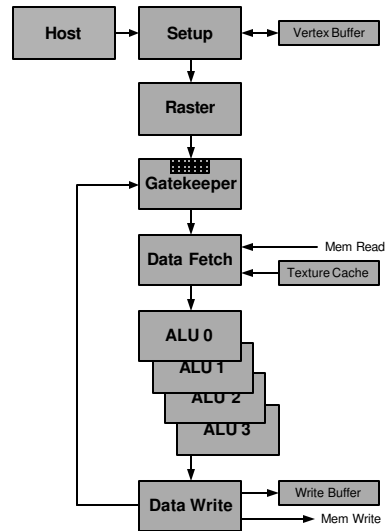
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## 3D Pipeline Overview

- **Setup – prepares triangles for rasterization**
- **Raster – interpolation of parameters**
- **Gatekeeper – scoreboarding and data flow control**
- **Data Fetch (DF) – color, depth, texture data reads**
- **Arithmetic Units (ALUs) – blending/combiner ops**
- **Data Write (DW) – color & depth writeback**

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# 3D Block Diagram



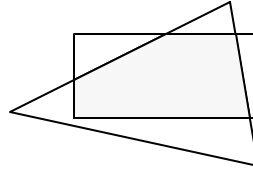
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## Setup Unit

- Simple packet-based host interface
- 32-bit IEEE float, S15.16 fixed and packed .8 inputs
- Up to 24 parameters + x,y,z,w per triangle
  - meaning of parameters left up to software
- Large vertex cache (software controlled)
- Performs simple transform, clip & viewport (1/w)
- Culls back-facing triangles
- Calculates interpolated LOD quantity per vertex

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# Raster Unit

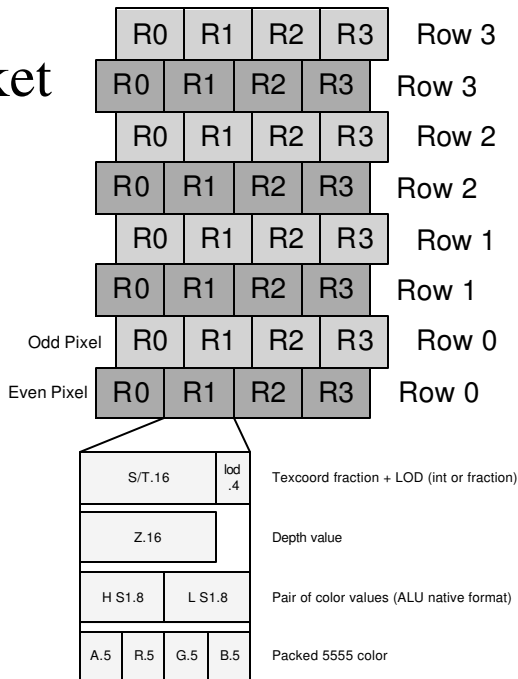


- Iterates intersection between triangle and scissor rectangle
- Supports “free” guard-band clipping
  - reduces complex clipping cases by 10x
- Follows OGL-ES/D3DM rasterization rules
- Generates pixel packets used by rest of pipe
  - 4 high-precision and 4 low-precision perspective-correct iterated values per row (plus Z for “free”)
  - span location (X,Y) sent via SPAN\_START packet
  - even/odd pixels interleaved to hide ALU latency
- Reduces precisions as early in pipeline as possible

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# Pixel Packet

**Packet contains iterated data and sideband information about even/odd, kill and instruction sequence**



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## Gatekeeper (GK) Unit

- **Controls pixel packet flow via counting**
  - keeps pipeline as full as possible during recirculation
  - tracks recirculated X,Y positions
- **Prevents coincident pixels from entering shader**
  - scoreboarding via bitmap marks X,Y pairs busy
- **Detects pipeline idle condition**
- **Collects debug readback info from shader blocks**
- **Maintains cache coherency**

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## Data Fetch (DF) Unit

- **8 instructions (e.g. 4 rows w/ 2 recirculations)**
- **8 surfaces (color, depth and up to 6 textures)**
- **One depth fetch per row (typically one per pixel), AND**
- **One color or filtered texture fetch per row**
  - supports RGBA, palettized and compressed formats
  - one clock nearest/bilinear, two clocks per trilinear
  - replaces texcoords with fetched 40-bit color (S1.8)
- **Manages color/depth and texture caches separately**
- **Performs depth test, marking pixel killed on failure**
  - Z-write deferred till semantically correct place

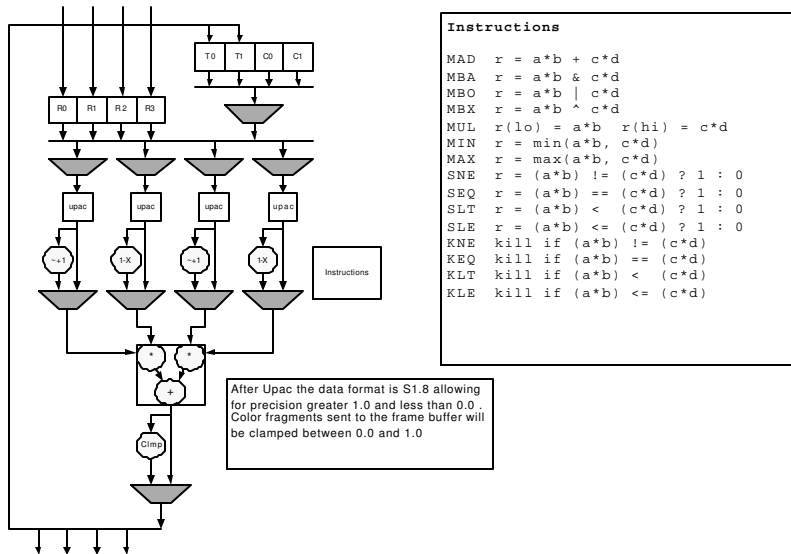
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# Arithmetic Logic (ALU) Units

- 8 instructions
- Performs  $a*b + c*d$  on one S1.8 scalar per row
- Operates on 4 20-bit R variables from row
- Can use 2 20-bit constants per unit (read-only)
- Can also use 2 20-bit temporary values per unit
  - const/temps can be 4 values in S1.8 format,
  - 8 values if 5555 packing is used
  - both are software loadable
- Can complement/negate operands, clamp result
- 4 ALU units in SC10 (typically one per channel)

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## ALU Block Diagram



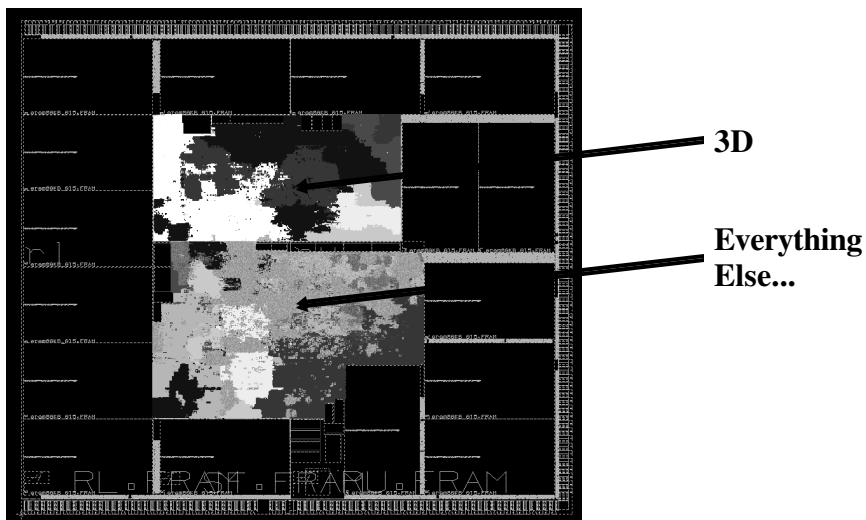
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# Data Write (DW) Unit

- 8 instructions
- Write coalescing buffers for color and depth
  - can write to all 8 surfaces at lower performance
- Optionally dithers to 565 color
- Suppresses killed pixel writes
- Indicates retired writes to GK for scoreboarding

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# SC10 Chip Plot



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# Power Reduction Techniques

- **Hardware Co-Processor Engines**
  - **2D/3D Graphics Engines, Graphics Controller**  
**Video Input Port, Flat Panel Interface**
- **Low Leakage Process**
- **Embedded Memory**
- **Relaxation Oscillator**
- **Fully Asynchronous Clocking**
- **Dynamic Clock Switching**
- **Sub-Module Clock Gating**
- **Automatic Pipeline Shutdown**

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# Multimedia Statistics

## ● **6.8M transistors in UMC 0.15 $\mu$ LL**

Use Case	Conditions	Core Power (mW)
1.3MP JPEG Decode	15fps @ 1.3MP Continuous Decode	10.6 mW
1.3MP JPEG Encode	15fps @ 1.3MP Continuous Encode	19.9 mW
MPEG4 Decode	CIF @ 30fps	13.1 mW
MPEG4 Encode	CIF @ 30fps	28.1 mW

CVDD = 1.5V  
FVDD = 3.3V

QVGA TFT LCD Display  
1.3MP CMOS Camera

BVDD = 3.3V  
VVDD = 2.8V

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# 3D Statistics

- 3.7M transistors in UMC 0.15 $\mu$ LL
- Capable of:
  - useful pixels at 1 clock/pixel (color + texture + depth)
  - complex at 2 clocks/pixel (e.g. + blending or 2<sup>nd</sup> texture)
  - supporting 4 textures with all OGL-ES features enabled
- Measured pixel fill-rates of 96% theoretical peak on XSCALE/ Accelent development system
- Given 1 vertex/triangle, can draw ~1M tris/sec at 72MHz (988k triangles/sec measured on XSCALE/Accelent system)
- Preliminary core power measurements at 1.5V/72MHz show apps (furry demo, Quake II) consume ~50-75mW at 30FPS
  - Drivers not yet tuned for power

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# 3D Examples



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